

The assignee of the entire right, title, and interest in and to the above-referenced patent application is Intel Corporation ("Assignee"),
(Name of Assignee)

a Delaware corporation having a place of business at
(State of Incorporation)

2200 Mission College Blvd., Santa Clara, California, 95052.
(Address)

The terminal part of any patent granted on the above-identified application that would extend beyond the expiration of the full statutory term of

X United States Patent No. 6,643,132, entitled
CHASSIS-LEVEL THERMAL INTERFACE COMPONENT FOR
TRANSFER OF HEAT FROM AN ELECTRONIC COMPONENT
OF A COMPUTER SYSTEM, and dated
November 4, 2003, as presently shortened

by any terminal disclaimer,

any patent granted on application number 0_/

is hereby disclaimed, except as provided below, and it is agreed that any patent so granted on the above-identified application shall be enforceable only for and during such period that the legal title to said patent shall be the same as the legal title to

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Any patent granted on application number 0_/

this agreement to run with any patent granted on the above-identified application and to be binding upon the grantor, its successors, or assigns.

No disclaimer is being made as to any terminal part of any patent granted on the above-identified application prior to the expiration of the full statutory term of

 X United States Patent No. 6,643,132 , as presently shortened by any terminal disclaimer,

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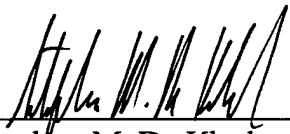
in the event that it later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. § 1.321(a), has all claims canceled by a reexamination certificate, is reissued, or is otherwise terminated prior to expiration of its statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

Enclosed is a check for \$130 for the fee under 37 C.F.R. § 1.20(d).

Please charge Deposit Account No. 02-2666 for any fee deficiency that may be due. A duplicate of this Terminal Disclaimer is enclosed for Deposit Account charging purposes.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



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Dated: January 19, 2006

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